

PART No.	CODE No.	POS.	B	C	D
BM23PF0.8-10DP-0.35V(51)	-	10	3.49	1.40	2.70
BM23PF0.8-14DP-0.35V(51)	-	14	4.19	2.10	3.40
BM23PF0.8-20DP-0.35V(51)	-	20	5.24	3.15	4.45
BM23PF0.8-24DP-0.35V(51)	-	24	5.94	3.85	5.15
BM23PF0.8-30DP-0.35V(51)	-	30	6.99	4.90	6.20
BM23PF0.8-40DP-0.35V(51)	-	40	8.74	6.65	7.95
BM23PF0.8-42DP-0.35V(51)	-	42	9.09	7.00	8.30
BM23PF0.8-44DP-0.35V(51)	-	44	9.44	7.35	8.65
BM23PF0.8-46DP-0.35V(51)	-	46	9.79	7.70	9.00
BM23PF0.8-50DP-0.35V(51)	-	50	10.49	8.40	9.70
BM23PF0.8-54DP-0.35V(51)	-	54	11.19	9.10	10.40
BM23PF0.8-64DP-0.35V(51)	-	64	12.94	10.85	12.15

NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

2. CONTACT PLATING SPECIFICATIONS.

CONTACT AREA : GOLD 0.05 μ m MIN.

SMT LEAD : GOLD 0.05 μ m MIN.

UNDER PLATING : NICKEL 1 μ m MIN.

(SURFACE : SEALING)

3. METAL FITTING PLATING SPECIFICATIONS.

SMT LEAD : GOLD 0.05 μ m MIN.

UNDERPLATING : NICKEL 1 μ m MIN.

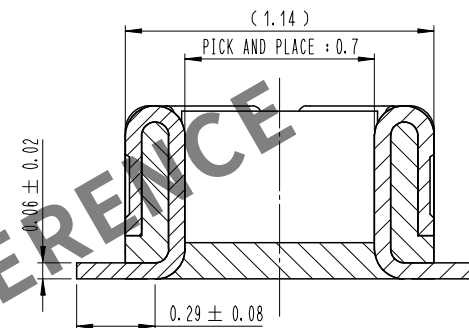
(SURFACE : SEALING)

4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.

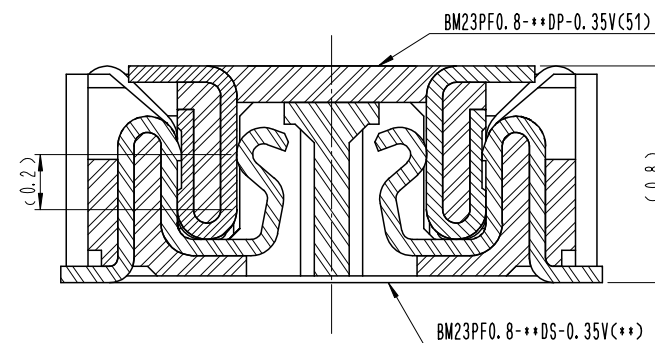
5. A PART OF THE WALL COULD BE NOTCHED.

COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
2	RE-6-0742	LYJ	JHW	16.09.27		3	RE-6-1784	PSH	JHW	20.04.09	
3	RE-6-0806	MSH	JHW	17.01.05							
1	RE-6-1137	KBJ	JHW	19.02.14							

A:A(50:1)



ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)				7	PS	CLEAR(REINFORCEMENT COLLAR)			
3	COOPER ALLOY	3				6	PS	BLACK (PLASTIC REEL)			
2	COOPER ALLOY	2				5	POLYESTER	CLEAR (COVER TAPE)			
1	LCP	UL94 V-0, BLACK									
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS	REMARKS					
						DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED	
						J. S. JANG	J. S. JANG	H. W. JO	H. W. JO	20.10.06	
						20.10.06	20.10.06	20.10.06	20.10.06		
						PART NO. BM23PF0.8-**DP-0.35V(51)					
						CODE NO CL 66*-*****-51					
						1/3					

CODE NO. (OLD)



DRAWING NO.

EDC3-*****

PART NO.

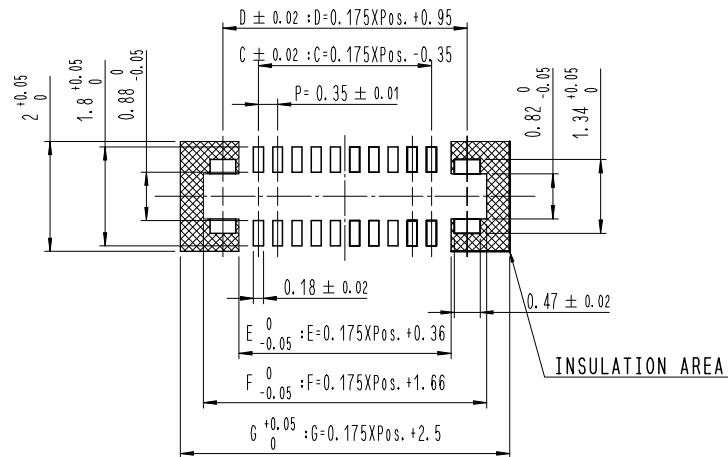
BM23PF0.8-**DP-0.35V(51)

CODE NO

CL 66*-*****-51

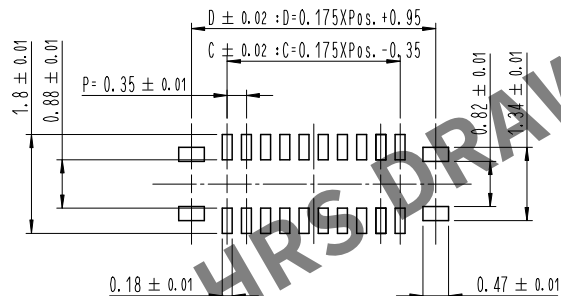
1/3

7 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS

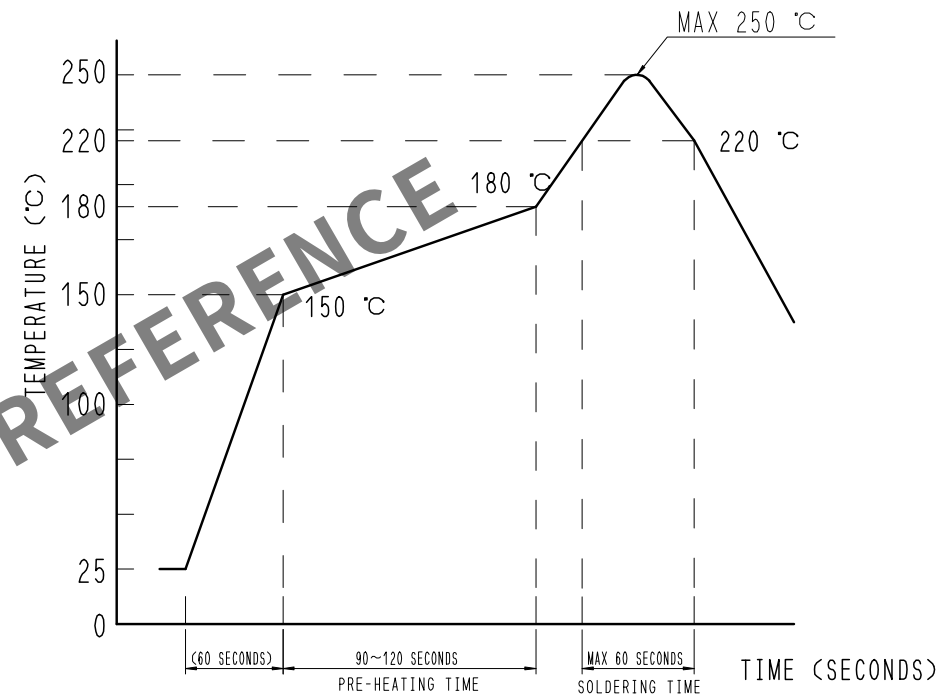
METAL MASK THICKNESS : $100 \mu m$



2/3/4

POS.	C	D	E	F	G
10	1.40	2.70	2.11	3.41	4.25
14	2.10	3.40	2.81	4.11	4.95
20	3.15	4.45	3.86	5.16	6.00
24	3.85	5.15	4.56	5.86	6.70
30	4.90	6.20	5.61	6.91	7.75
40	6.65	7.95	7.36	8.66	9.50
42	7.00	8.30	7.71	9.01	9.85
44	7.35	8.65	8.06	9.36	10.20
46	7.70	9.00	8.41	9.71	10.55
50	8.40	9.70	9.11	10.41	11.25
54	9.10	10.40	9.81	11.11	11.95
64	10.85	12.15	11.56	12.86	13.70

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N_2 REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150°C
PRE-HEAT TEMPERATURE (MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-**DP-0.35V(51)
	SCALE	10:1	CODE NO	CL 66*-*****-51
UNITS	HRS HIROSE KOREA CO., LTD.		2/3	

